Ultra Precision Laser Machining for Microelectronics

QP Technologies offers the following:

- Silicon wafer coring from wafers as large as 12” (305mm); custom extraction of smaller development wafers
- Laser cutting, drilling and marking
- Evaluation of product or process feasibility
- Consultation in laser material processing
- Development and optimization of production processes
- Large-volume jobs
- Pilot and short-run production
- Test samples and prototypes
- File translation for CAM
- Laser stencils

In the world of high-density microelectronics packaging, precision is everything. That is why QP Technologies has invested in state-of-the-art laser machining technology, offering unparalleled accuracy for all your micromachining needs.